

SMD High Voltage Class I

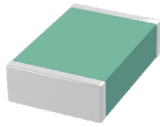
1KV - 15KV



SRT
MICROCÉRAMIQUE
MLCC CAPACITORS

APPLICATIONS

- Typical uses : timing, precision circuitry, filtering



RoHS
compliant

FEATURES

- Ultra stable temperature compensating class I ceramic
- Custom voltage, package size, capacitance value on request
- Tested in accordance to CECC 32100 and AEC-Q200
- CECC 30600 et NFC 83-131 compliant
- Available in stack or radial
- Surface coating can be necessary to prevent surface arcing

ELECTRICAL PARAMETERS

ELECTRICAL CHARACTERISTICS :
at + 25°C unless otherwise specified

OPERATING TEMPERATURE :
- 55°C, + 125°C

TEMPERATURE COEFFICIENT :
± 30ppm with 0Vdc applied

DISSIPATION FACTOR :
≤ 1.10-3 at 1Vrms and 1MHz for values ≤ 1000pF
≤ 1.10-3 at 1Vrms and 1kHz for values > 1000pF

INSULATION RESISTANCE (IR) :
25°C/Un 10⁵ MOhm or 1000 Ohm-Farad whichever is less
125°C/Un 10⁴ MOhm or 100 Ohm-Farad whichever is less

DIELECTRIC STRENGTH TEST :
1.2Un for 5s with 50mA max charging current

QUICK REFERENCE DATA

	0805	1206	1210	1808	1812	1825	2220	2225	2825	3640	4040	5440	5550	6660	8060	80150	15080
Min	0.1 pF	0.4 pF	0.4 pF	1.0 pF	1.0 pF	1.0 pF	1.0 pF	1.0 pF	4.7 pF	10 pF	10 pF	10 pF	10 pF	10 pF	10 pF	22 pF	22 pF
1KV	820 pF	2.7 nF	6.8 nF	6.8 nF	15 nF	33 nF	39 nF	47 nF	56 nF	120 nF	120 nF	180 nF	220 nF	330 nF	390 nF	1.0 μF	1.0 μF
1.5KV	330 pF	1.0 nF	2.7 nF	2.7 nF	8.2 nF	18 nF	18 nF	27 nF	33 nF	68 nF	68 nF	100 nF	120 nF	180 nF	220 nF	560 nF	560 nF
2KV	150 pF	560 pF	1.5 nF	1.2 nF	3.9 nF	10 nF	12 nF	15 nF	18 nF	39 nF	47 nF	56 nF	82 nF	120 nF	120 nF	330 nF	330 nF
3KV		180 pF	470 pF	470 pF	1.2 nF	2.7 nF	2.7 nF	3.9 nF	4.7 nF	10 nF	12 nF	15 nF	18 nF	27 nF	33 nF	82 nF	82 nF
4KV		82 pF	220 pF	220 pF	680 pF	1.8 nF	1.8 nF	2.2 nF	3.3 nF	6.8 nF	8.2 nF	10 nF	12 nF	18 nF	22 nF	56 nF	56 nF
5KV				150 pF	390 pF	1.0 nF	1.2 nF	1.8 nF	2.2 nF	4.7 nF	5.6 nF	6.8 nF	8.2 nF	12 nF	15 nF	39 nF	39 nF
8KV				47 pF	150 pF	330 pF	330 pF	470 pF	560 pF	1.2 nF	1.5 nF	1.8 nF	2.2 nF	3.3 nF	3.9 nF	10 nF	10 nF
10KV				27 pF	82 pF	220 pF	270 pF	330 pF	390 pF	820 pF	1.0 nF	1.2 nF	1.8 nF	2.2 nF	2.7 nF	6.8 nF	6.8 nF
12KV										560 pF	680 pF	820 pF	1.0 nF	1.5 nF	1.8 nF	4.7 nF	4.7 nF
15KV										330 pF	390 pF	560 pF	680 pF	1.0 nF	1.2 nF	2.7 nF	2.7 nF

ORDERING INFORMATION

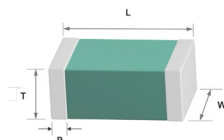
5440	A	101	K	H	X	B	-
SIZE	DIELECTRIC	CAPACITANCE	TOLERANCE	VOLTAGE	TERMINATION	PACKAGING	SPECIAL PARAMETERS
0805 1206 1210 1808 1812 1825 2220 2225 2825 3033 3640 4040 4055 5440 5550 6660 8060 80150 15080	A = NPO	Expressed in picofarads (pF). The first two digits are significant, the third digit gives the number of noughts. Example : 102 = 1 000pF For special values R is used as decimal separator Example 12R7 = 12.7pF 1340R0 = 1340pF	A = ±0,5% if > 10pF and ±0,05pF si < 10pF B = ± 0,1pF C = ± 0,25pF D = ± 0,5pF E = 0.1% F = ± 1% G = ± 2% J = ± 5% K = ± 10%	G = 1KV O = 1.5KV H = 2KV T = 2.5KV I = 3KV K = 4KV L = 5KV 6 = 6KV 8 = 8KV 10 = 10KV 12 = 12KV 15 = 15KV	X = Nickel Tin F = Palladium-Silver P = Polymer Tin C = Copper Tin W = Nickel Gold Q = Solderable Silver	B = Reel V = Bulk	- BM = BME Dxx = Reliability spec Exx = Sorting spec

For other sizes, voltage, tolerance contact us

DIMENSIONS IN MILLIMETERS

	0805	1206	1210	1808	1812	1825	2220	2225	2825	3640	4040	5440	5550	6660	8060	80150	15080
Length (L)	2.00 ± 0.2	3.20 ± 0.2	3.20 ± 0.2	4.60 ± 0.3	4.60 ± 0.3	4.60 ± 0.4	5.60 ± 0.4	5.60 ± 0.4	7.10 ± 0.4	9.15 ± 0.8	10.20 ± 0.8	13.70 ± 1.0	14.00 ± 1.0	16.80 ± 1.0	20.30 ± 1.0	20.30 ± 1.0	20.30 ± 1.0
Width (W)	1.25 ± 0.2	1.60 ± 0.2	2.50 ± 0.2	2.00 ± 0.2	3.20 ± 0.2	6.35 ± 0.3	5.10 ± 0.4	6.35 ± 0.4	6.35 ± 0.4	10.20 ± 0.8	10.20 ± 0.8	10.20 ± 1.0	12.70 ± 1.0	15.20 ± 1.0	15.20 ± 1.0	38.10 ± 1.0	38.10 ± 1.0
Thickness max(T)	1.40	1.70	2.50	2.20	3.30	3.60	4.00	4.00	4.00	4.00	4.00	4.00	4.00	4.00	4.00	4.00	4.00
Termination (P)	Min	0.25	0.25	0.25	0.25	0.25	0.25	0.25	0.25	0.80	0.80	0.80	0.80	0.80	0.80	0.80	0.80
	Max	0.70	0.70	0.80	0.80	0.80	0.80	1.00	1.00	1.50	1.50	1.50	1.50	1.50	1.50	1.50	1.50

For P termination (Polymer type) add 0.10mm to Length (L) and 0.05 to Width (W)

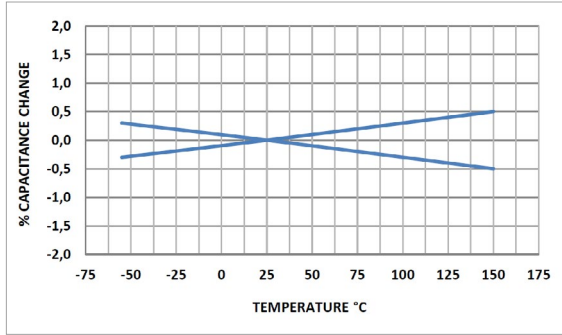


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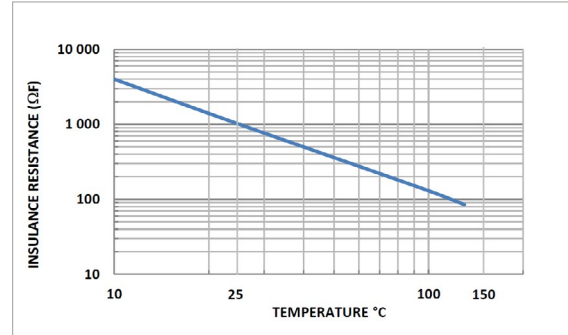


TYPICAL CHARACTERISTICS

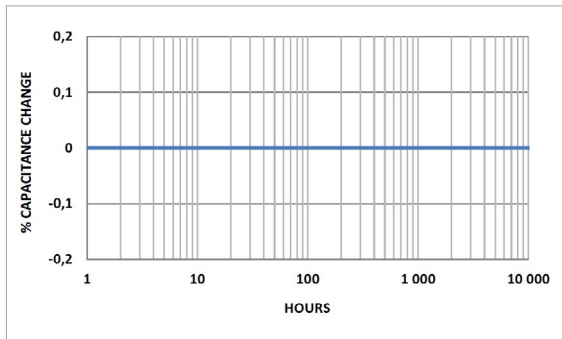
NPO Temperature coefficient of capacitance



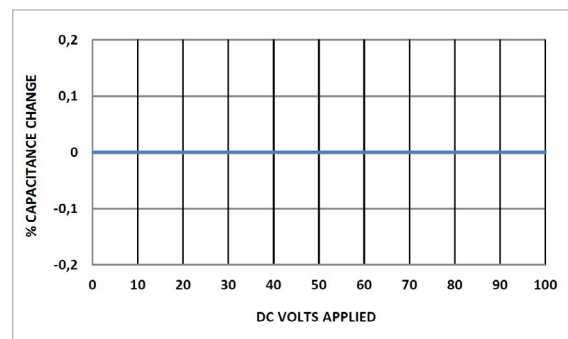
NPO Insulation resistance vs. temperature



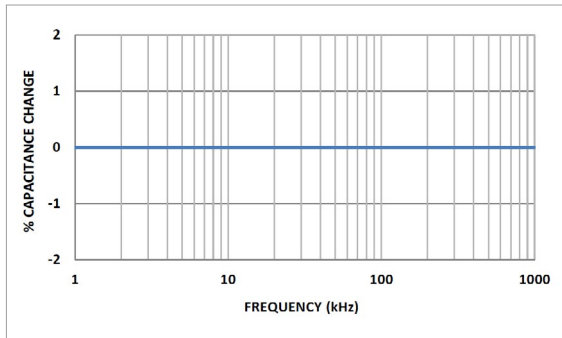
NPO Aging rate



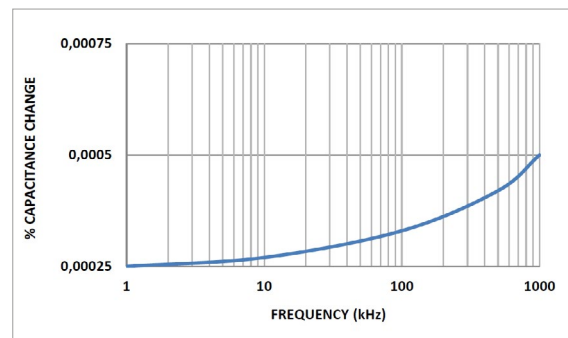
NPO Voltage coefficient of capacitance



NPO Change of Capacitance with Frequency



NPO Dissipation factor vs. frequency



Different types of dielectrics display very different behaviours when it comes to withstanding power and heat, and don't demonstrate the same capacitance potential. SRT-Microcéramique proposes a wide range of ceramics. You'll find in the page below more information about what type of ceramic is better suited to your needs.

Class I Dielectrics

Class I Dielectrics are the most stable type and are used when the application demands highly stable performance and cannot allow electrical noise or dielectric loss. Variations of voltage and temperature have minimum consequences on this class of dielectrics, consequently, they are most used for DC blocking, decoupling applications as well as filtering with low capacitance.

Q (Code Q)

- Most stable type
- Low capacitance
- Good for avoiding electrical noise

NPO (Code A)

- Most stable type
- Lower capacitance
- Good for avoiding electrical noise

Class 1.5 Dielectrics

Close to Class II capacitance and as stable than Class I

N2T (Code P)

- Ultra stable
- No piezo electric effect
- High current pulse discharge

Class II Dielectrics

Class II Dielectrics display stable performance and possess a better volumetric efficiency than class I. Thus, they are used in bypassing, filtering, coupling and decoupling applications.

X7R (Code Y)

- Good volumetric efficiency
- High capacitance
- stable

BX/BY (Code X/2C1)

- Improved ESR
- Better voltage coefficient
- MIL specifications

X5R/X7S/X6S/Y5V (Code R/T/S/V)

- Highest capacitance per volume
- Less stable
- Low voltage

Dielectric	Class I		Class 1.5	Class II						
	High Q	NPO/COG	N2T	X7R	BX	2C1	X5R	X7S	X6S	Y5V
SRT Code	Q	A	P	Y	X	2C1	R	T	S	V
Type	Ultra Stable			Stable						
Temperature Range	-55°C +125°C (250°C)		-55°C +125°C			-55°C +85°C		-55°C +125°C	-55°C +105°C	-25°C +85°C
T° Coefficient no DC applied	± 30ppm		2200ppm ± 350	± 15%		± 20%	± 15%	± 22%		+30% -80%
T° Coefficient rated DC applied	-		-	-	+15 -25%	+20 -30%	-	-	-	-
Dielectric constant	10-100		450	2000-3000			3000-20000			
Dissipation Factor	0.01% 0.05%	0.05% 0.1%		1% 3.5%			2.5% 15%		5% 20%	
IR 25°C/Un	100 GΩ or 1000 Ω-F whichever is less						10 GΩ or 100 Ω-F whichever is less			
Dielectric strenght ≤200V	2.5 Ur 5 seconds 50mA max									
Dielectric strenght <500V	Ur + 250V 5 seconds 50mA max									
Dielectric strenght <1000V	1.5 Ur 5 seconds 50mA max									
Dielectric strenght ≥1000V	1.2 Ur 5 seconds 50mA max									
Piezo effect	No piezo			piezo effect						
Ageing	None			2% per decade	1% per decade		4% per decade	5% per decade		7% per decade
Tolerance	± 0.25pF ± 0.5pF ± 1% ± 2% ± 5% ± 10%			± 5% ± 10% ± 20%			± 10% ± 20%		-20% +80%	
Termination	X,C,H		X,F,P,C,W,H,I			X,P		X		

All our capacitors are available with a wide range of termination to fit your specific needs :

Tin (Code X)

- Standard termination
- ROHS
- Dipped Silver, Nickel barrier, Sn plated

Polymer (Code P)

- Flexible termination
- Improve bending tolerance
- ROHS
- Available on all components
- Designed for gluing

Silver-Palladium (Code F)

- Excellent contact properties
- Resist to leaching during hand soldering
- Dipped Silver-Palladium
- ROHS

Gold Flash (Code W)

- Glueing
- ROHS
- Max 0.2µm Gold Flash

Gold Thick (Code W)

- Microelectronic applications
- Wire Bonding/glueing
- ROHS
- Min 2.5µm Gold

Non Magnetic (Code C/CP)

- High Tesla Applications
- IRM, particule accelerators
- Dipped Silver, Copper barrier, Sn plated
- ROHS

Solderable Silver (Code Q)

- Medical or space application
- Whiskers free
- High temperature
- ROHS

Dipped SAC 305 (Code S/SP)

- Sn96.5 Ag3 Cu0.5
- Medical, space and oil application
- Whiskers free
- High reliability
- ROHS

Dipped Tin-Lead (Code H/HP)

- Sn62 Pb36 Ag2
- Medical or Oil application
- Whiskers free
- High reliability

Electrolytical Tin-Lead (Code I/IP)

- Minimum Pb 10%
- Medical or space application
- Whiskers free
- High reliability

TERMINATION	CODE	ROHS	NON MAGNETIC	IMPROVED BOARD FLEX	SOLDERING	GLUING	WIRE BONDING
Sn	X	0			0		
Polymer	P	0		0	0		
AgPd	F	0			0	0	
Gold Flash	W	0			0	0	
Gold Thick	G	0			0	0	0
Non Magnetic	C	0	0		0		
Solderable Silver	Q	0			0		
Dipped SnPb	H				0		
Dipped SAC	S	0			0		
Electrolytical SnPb	I				0		
Lead	-	0		0	0		
Non Magn Lead	C	0	0	0	0		
Lead Frame	-	0		0	0		
Non Magn Lead Frame	C	0	0	0	0		

0 = COMPLIANT

STORAGE

To prevent the damage of solderability of terminations, the following storage conditions are recommended :

Indoors under 5 ~ 40°C and 20% ~ 70% RH.

No harmful gases containing sulfuric acid, ammonia, hydrogen sulfide or chlorine.

Packaging should not be opened until the capacitors are required for use. If opened, the pack should be re-sealed as soon as possible. Taped products should be stored out of direct sunlight, which might promote deterioration in tape or adhesion performance. The product is recommended to be used within 24 months after shipment. Extended shelf life over this period require a solderability check before use.

HANDLING

Chip capacitors are dense, hard, brittle, and abrasive materials. They are liable to suffer mechanical damage, in the form of cracks or chips. Chip Capacitors should be handled with care to avoid contamination or damage. To use vacuum or plastic tweezers to pick up or plastic tweezers is recommended for manual placement. Tape and reeled packages are suitable for automatic pick and placement machine.

PREHEAT

In order to minimize the risk of thermal shock during soldering, a carefully controlled preheat is required.

The rate of preheat should not exceed 3°C per second.

SOLDERING FLUX

Use mildly activated rosin RA and RMA fluxes, but do not use activated flux. The amount of solder in each solder joint should be controlled to prevent the damage of chip capacitors caused by the stress between solder, chips, and substrate.

SOLDERING TYPE

Lead containing solders, such as Sn60, Sn62 or Sn63 and lead free solders, such as SnAgCu, can all be used with our MLCCs.

In case of non-magnetic termination code C, use lead containing or lead (Pb)-free SAC305 solders.

SOLDERING HEIGHT

The solder climbing minimum height is suggesting to 25% of chip thickness or 500um whichever is less.

(Reference from IPC-610E)

COOLING

After soldering, cool the chips and the substrate gradually to room temperature. Natural cooling in air is recommended to minimize stress in the solder joint.

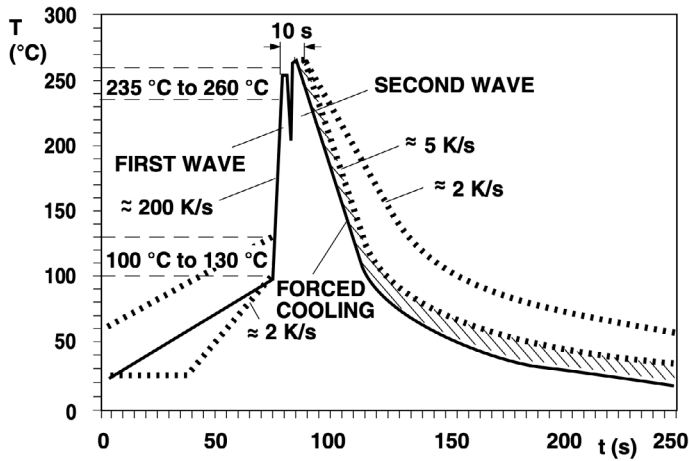
CLEANING

All flux residues must be removed by using suitable electronic-grade vapor-cleaning solvents to eliminate contamination that could cause electrolytic surface corrosion. Good results can be obtained by using ultrasonic cleaning of the solvent. The choice of the proper system is depends upon many factors such as component mix, flux, and solder paste and assembly method. The ability of the cleaning system to remove flux residues and contamination from under the chips is very important.

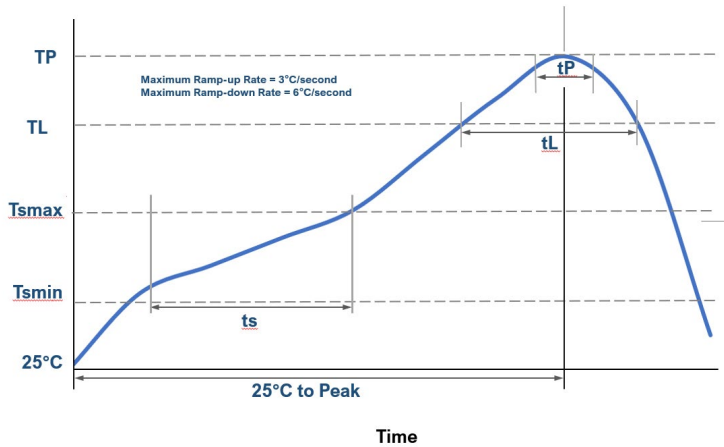
SOLDERING CONDITIONS

SIZE	THICKNESS	WAVE	REFLOW
0402	All	0	0
0505	All	0	0
0603	All	0	0
0805	< 1.25mm	0	0
0805	≥ 1.25mm	0	0
1111	< 1.25mm	0	0
1111	≥ 1.25mm	0	0
1206	< 1.25mm	0	0
1206	≥ 1.25mm	0	0
1210	< 1.25mm	0	0
1210	≥ 1.25mm	0	0
larger than 1210	All	0	0
High compact	All	0	0

WAVE SOLDERING PROFILE

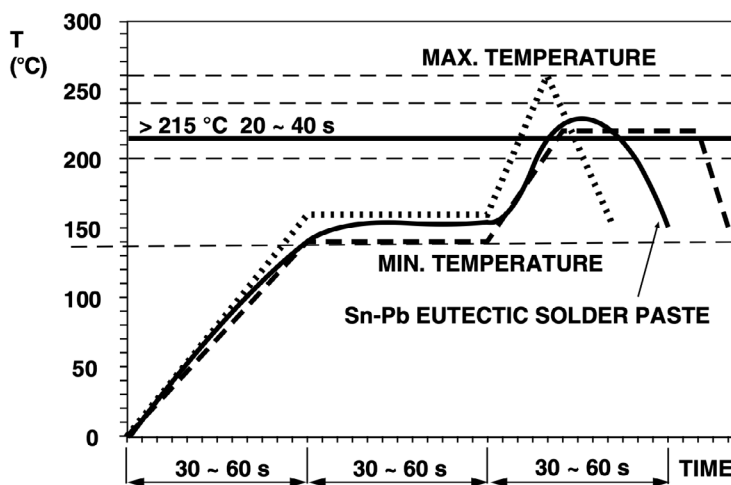


LEADFREE REFLOW SOLDERING PROFILE



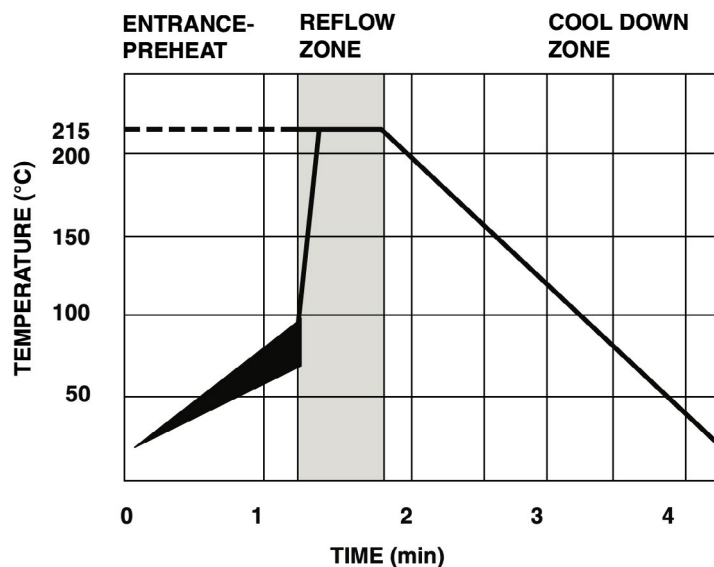
PROFILE FEATURE	LEAD FREE (SAC 305)
Tsmin	150°C
Tsmax	190°C
Time from Tsmin to Tsmax	60 - 120 seconds
Ramp-up Rate	3°C/second max
Liquidous Temperature	217°C
Time above Liquidous	60 - 120 seconds
Peak Temperature	250°C
Time within 5°C of maximum	10 seconds max
Peak Temperature	250°C
Ramp-down Rate	6°C/second max
Time 25°C to Peak	8min max

SNPB REFLOW SOLDERING PROFILE



VAPOUR PHASE REFLOW PROFILE

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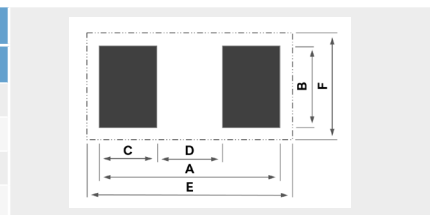
HAND SOLDERING

Hand soldering is not recommended as the thermal shock may cause a crack, however if used the following recommendations should be taken :

- Soldering iron tip diameter ≤ 3.0 mm and wattage max. 20W.
- The Capacitors shall be pre-heated to 150°C and that the temperature gradient between the devices and the tip of the soldering iron.
- Tip temperature ≤ 280 °C and should't be applied for more than 5 seconds.
- The required amount of solder shall be melted on the soldering tip.
- The tip of iron should not contact the ceramic body directly.
- The Capacitors shall be cooled gradually at room temperature after soldering.
- Forced air cooling is not allowed.

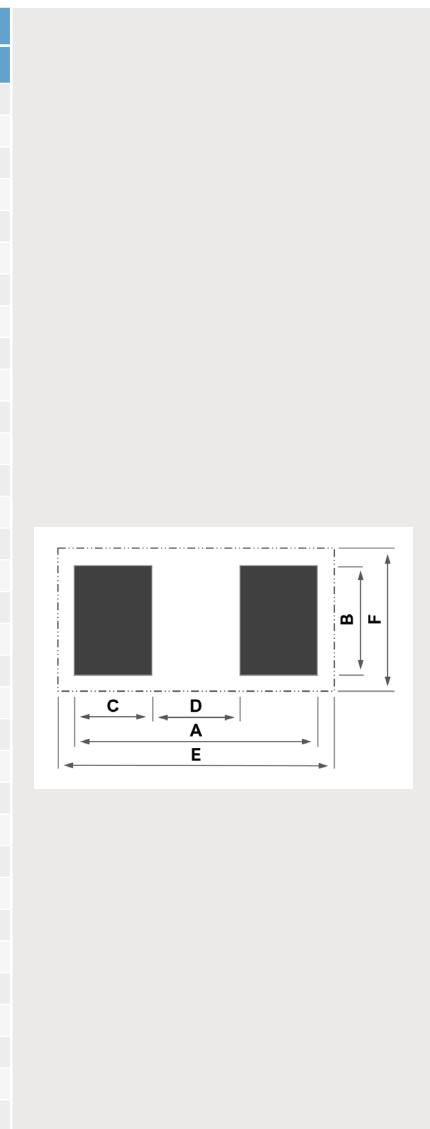
TYPICAL SMD FOOTPRINT WAVE SOLDERING

SIZE	FOOTPRINT DIMENSIONS IN MM					
	A	B	C	D	E	F
0603	2.40	0.80	0.70	1.00	3.10	1.40
0805	3.20	1.30	0.90	1.40	4.10	1.85
1206	4.80	1.70	1.25	2.30	5.90	2.25
1210	4.80	2.60	1.25	2.30	5.90	3.15



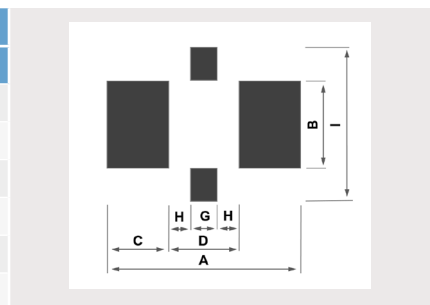
TYPICAL SMD FOOTPRINT REFLOW SOLDERING

SIZE	FOOTPRINT DIMENSIONS IN mm					
	A	B	C	D	E	F
0201	0.65	0.30	0.21	0.23	0.90	0.60
0204	1.00	1.00	0.30	0.40	1.25	1.45
0402	1.50	0.50	0.40	0.70	1.75	0.95
0306	1.30	1.60	0.40	0.50	1.55	2.05
0404	1.50	1.00	0.40	0.70	1.75	1.45
0504	1.90	1.00	0.40	1.10	2.15	1.45
0505	1.90	1.30	0.50	0.80	2.15	1.75
0508	1.90	2.00	0.50	0.90	2.15	2.55
0603	2.30	0.80	0.60	1.10	2.55	1.35
0612	2.30	3.20	0.60	1.10	2.55	3.75
0805	2.90	1.25	0.90	1.10	3.15	1.80
1206	4.10	1.60	0.90	2.30	4.35	2.25
1210	4.10	2.50	1.00	2.10	4.35	3.15
1808	5.50	2.10	1.20	3.10	5.75	2.75
1812	5.50	3.30	1.20	3.10	5.75	3.95
1825	5.50	6.55	1.20	3.10	5.75	7.20
2211	6.80	3.00	1.40	4.00	7.05	3.65
2220	6.80	5.40	1.40	4.00	7.05	6.05
2225	6.80	6.70	1.65	3.50	7.05	7.50
2525	7.70	6.75	1.65	4.40	7.95	7.55
2825	8.40	6.70	1.65	5.10	8.65	7.50
3033	9.00	8.80	1.95	5.10	9.25	9.60
3640	10.55	10.70	2.35	5.85	10.80	11.50
4040	11.60	10.70	2.35	6.90	11.85	11.50
40100	11.60	26.20	2.35	6.90	11.85	27.00
5550	15.50	13.20	2.35	10.80	15.75	14.00
6080	16.70	20.80	2.35	12.00	16.95	21.60
6660	18.30	15.70	2.35	13.60	18.55	16.50
8060	21.90	15.70	2.35	17.20	22.15	16.50
80150	21.90	38.90	2.35	17.20	22.15	39.70
HIGH COMPACT 1210	4.15	2.60	1.15	1.85	5.05	3.30
HIGH COMPACT 1812	5.75	3.40	1.35	3.05	6.70	4.20
HIGH COMPACT 2220	6.80	5.50	1.70	3.40	7.70	6.30



TYPICAL FILTER FOOTPRINT REFLOW SOLDERING

SIZE	FOOTPRINT DIMENSIONS IN mm						
	A	B	C	D	G	H	I
0603	2.30	0.80	0.45	1.40	0.60	0.40	1.50
0805	2.90	1.25	0.90	1.80	0.80	0.50	2.00
1206	4.10	1.60	0.90	2.40	1.00	0.70	3.00
1806	5.50	1.60	1.20	3.20	1.00	1.10	3.00
1812	5.50	3.30	1.20	3.90	1.50	1.20	4.80
2220	6.80	5.40	1.40	4.50	1.50	1.50	7.00





ORDERING INFORMATION

SRMC	0603	Y	102	J	A	-	L	040	-	-	-	B	-
SERIE	SIZE	DIELECTRIC	CAPACITANCE	TOLERANCE	VOLTAGE	TERMINAISON	FORM	HEIGHT	LEADS	COATING	CUR-RENT	PACKAGING	SPECIAL
-	0201	Q = High Q	Expressed in picofarads (pF)	A = ± 0.05pF/0.1%	Y = 4V	- = Sn lead/lead frame	-	020	-	-	-	B = Reel	-
FK	0204	A = NPO		B = ± 0.1pF	R = 6.3V	X = Nickel Tin	J	030	2 to 10	-	1	V = Bulk	BM = BME
FH	0402	P = N2T	The first two digits are significant,	C = ± 0,25pF	Q = 10V	F = Palladium-Silver	L	040	B	I = Conformal-Coating	2	T = Tray Package	Dxx = Reliability spec
SREV	0303	X = BX	the third digit gives the number of noughts	D = ± 0,5pF	J = 16V	P = Polymer Tin (Flex)	D	050		H = EpoxyCoating		W = Waffle Pack	Exx = Sorting spec
MCF	0306	Y=X7R		E = ± 0.5%	X = 25V	C = Copper Tin (Non magnetic)	M	060					H = High Reliability
M2F	0404	BY=2C1		F = ± 1%	Z = 35V	CP = Copper Polymer Tin (Non magnetic)	T = 2	070					Q = Anti-Arcing
MPF	0505	T = X7S	Example : 102 = 1 000pF	G = ± 2%	A = 50V	W = Nickel Gold Flash	leads	080					E = Anti Bending
SRMC	0508	S = X5R		J = ± 5%	U = 63V	G = Nickel Gold Thick	U = 4	090					Z = Anti-Arcing + Anti-Bending
SRTV	0603	R = X6S		K = ± 10%	B = 100V	HP = Dipped SnPb Polymer	leads	100					
SR	0612	V = Y5V	For special values R is used as decimal separator	M = ± 20%	C = 200V	H = Dipped SnPb		110					
SA	0805	U = X8R	Example 12R7 = 12.7pF	Z = -20% +80%	P = 250V	S = Dipped SAC		120					
H	1206		Example 1340R0 = 1340pF		D = 300V	SP = Polymer Dipped SAC		130					
	1210				E = 500V	I = Electrolytic SnPb		140					
	1808				F = 630V	IP = Polymer Electrolytical SnPb		160					
	1812				G = 1000V	Q = Solderable Silver		180					
	1825				O = 1500V	M = Microstrip							
	2211				H = 2000V	A = Axial Ribbon							
	2220				T = 2500V	R = Radial Ribbon							
	2225				I = 3000V	U = Axial Wire							
	2325				K = 4000V	V = Radial Wire							
	2525				L = 5000V	CM = Microstrip (Non magnetic)							
	2825				6 = 6000V	CA = Axial Ribbon (Non magnetic)							
	3033				S = 7200V	CR = Radia Ribbon (Non magnetic)							
	3640				8 = 8000V	CU = Axial Wire (Non magnetic)							
	4040				10 = 10000V	CV = Radial Wire (Non magnetic)							
	40100				12 = 12000V								
	5550				15 = 15000V								
	6080												
	6660												
	7274												
	8060												
	80150												
	15080												
	40 to 94												

RELIABILITY

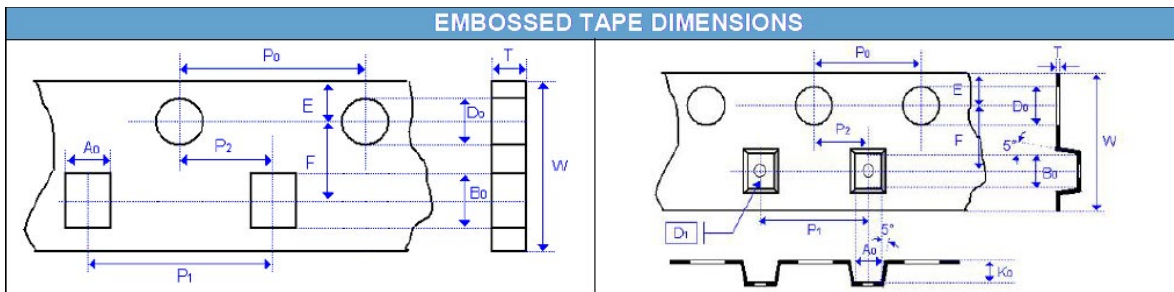
OPTIONAL CODE	TESTING DETAIL
D03	Burn-In 100% 125° 168H, no default allowed
D05	Burn-In 100% 125° 168H, less than 5% default allowed VRT CEI 68-2-14 10 cycles 0V -55°C/+125°C, less than 5% default allowed 20 pieces life test 125°C, 1.5Un, 1 default allowed
D20	AECQ-200
D30	Screened and LAT according to ECSS-3009 for space application
D32	Evaluation version for space development according to ECSS-2310
COTS1	Class 1 COTS+ according to ECSS-Q-ST-60-13C-Rev1
COTS2	Class 2 COTS+ according to ECSS-Q-ST-60-13C-Rev1
COTS3	Class 3 COTS+ according to ECSS-Q-ST-60-13C-Rev1

SORTING

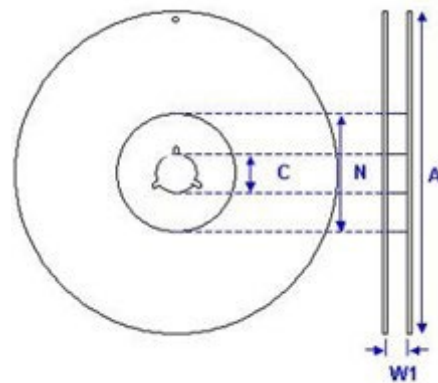
OPTIONAL CODE	SORTING DETAIL
E01	2 cells sorting 0 to +2,5 & +2,5 to +5 (% or pF according to value)
E02	4 cells sorting -5 to -2,5 ; -2,5 to 0 ; 0 to +2,5 & +2,5 to 5 (% or pF according to value)
E21	2% cells

PACKAGE DIMENSION AND QUANTITY

SIZE	THICKNESS	PAPER TAPE		PLASTIC TAPE	
		7 REEL	13 REEL	7' REEL	13 REEL
0402	0.5 ± 0.05	10 K	50 K		
0504	0.6 ± 0.05			4K	15K
	0.9 ± 0.05			4K	15K
0603	0.7 ± 0.07	4K		4K	15K
	0.9 ± 0.07	4K	15K	4K	15K
	0.9 ± 0.07			4K	15K
	1.1 ± 0.07			4K	15K
0805	0.8 ± 0.07	4K	15K	4K	15K
	0.9 ± 0.07			4K	10K
	1.1 ± 0.07			3K	10K
	1.3 ± 0.07			3K	10K
1206	1.1 ± 0.1			3K	10K
	1.4 ± 0.1			3K	8K
	1.8 ± 0.1			2K	8K
1210	1.4 ± 0.1			3K	8K
	1.8 ± 0.1			1K	6K
1808	1.4 ± 0.1			3K	8K
1812	1.6 ± 0.1			2K	8K
	2.1 ± 0.1			1K	6K
	2.8 ± 0.1			1K	6K
2220	1.8 ± 0.1			1K	6K
	3.0 ± 0.1			0.5K	2K
2225	3.0 ± 0.1			0.5K	2K
3033	3.0 ± 0.1			0.5K	2K
3640	3.0 ± 0.1			0.5K	2K
5440	3.9 ± 0.1				0.5K - 1K
HIGH COMPACT 1210				1K	6K
HIGH COMPACT 1812				1K	6K
HIGH COMPACT 2220				0.5K	2K



REEL SIZE	7	7	13
C	13.0 +0.5/-0.2	13.0 +0.5/-0.2	13.0 +0.7/-0.3
W1	8.4 +1.5/-0	12.4 +2.0/-0	8.4 +2.0/-0
A	178.0 ±0.10	178.0 ±0.10	330.0 ±1.0
N	60.0 ±1.0	80.0 ±1.0	100 ±1.0



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RELIABILITY PRINCIPLES OVERVIEW GENERAL PRODUCTION

In order to guarantee highly reliable products to their customers, SRT-Microcéramique follows a strict quality policy which is explained below :

- According to AECQ philosophy, each component belongs to a family, which most restrictive members (four corners) have been fully qualified.
- PME components are produced in our Vendôme facility, with very stable process and equipments, in order to ensure Reliability and reproductibility.
- Reliability is based on batch tests, new product or equipment-specific qualifications and periodic requalifications.
- In addition to those regular tests, our quality departement launches regular accelerated tests to further deepens our reliability datas.
- Tests and qualifications of our standard products are based on AECQ methodology and are qualified according to the following limits.
- In accordance to AECQ methodology, specifics tests and limits can be adapted to fit our clients' needs.
- A whole range of stricter reliability tests can be offered for high Reliability products (burn-in, shocks, pulses...) for medical, space and defense applications.
- Based on our reliability database, FIT datas can be provided if necessary.

PRODUCTION CONTROL

Test conducted on each lot according to AECQ-200 framework

FREQUENCY	TEST/STRESS	REFERENCE	AEC-Q	DETAIL
100%	Capa, DF, IR	CECC-32100-4.6		according to datasheet
100%	Visual	CECC-32100-4.5	AEC-Q200-9	no visual defects
50/lot	DPA		AEC-Q200-5	internal component integrity
5/lot	Dimension	CECC-32100-4.5	AEC-Q200-5	according to datasheet
5/lot	Resistance to soldering heat	CECC-32100-4.10	AEC-Q200-15	
5/lot	Solderability	CECC-32100-4.11	AEC-Q200-18	
10/lot	Voltage proof	CECC-32100-4.6.4		
1/ceramic lot	Temperature coefficient	CECC 32100-Prgph4,7		according to datasheet

QUALIFICATIONS

Each component family has been qualified according to CECC and AECQ tests methodology, which are renewed on a periodic basis.

FREQUENCY	TEST/STRESS	REFERENCE	AEC-Q	DETAIL
Qualif	Electrical Characterization	CECC-32100-4.6 4.7	AEC-Q200-19	measure before test according to datasheet and after test according to post environmental limits
Qualif	Temperature Cycling	JESD22 Method-JA method 104	AEC-Q200-4	1,000 cycles -55°C to +125°C Measurement at 24 ± 2 hours after test conclusion
Qualif	Biased Humidity	MIL-STD-202 Method 103	AEC-Q200-7	1,000 hours 85°C/85%RH. Rated voltage. Measurement at 24 ± 2 hours after test conclusion
Qualif	Operational Life	MIL-STD-202 Method 108 condition D	AEC-Q200-8	1,000 hours at 125°C with applied Voltage : 2xRV RV≤500V, 1.2xRV 500V<RV≤1250V, RV RV>1250V
Qualif	High Temperature Exposure (Storage)	MIL-STD-202 Method 108	AEC-Q200-3	1,000 hours at 150°C with 0V. Measurement at 24 ± 2 hours after test conclusion
Qualif	Terminal Strength	CECC-32100-4.8	AEC-Q200-6	1.8kg 60 seconds
Qualif	Vibration	MIL-STD-202 Method 204	AEC-Q200-14	5g 20min 12cycles 3 orientations 10-2000Hz
Qualif	Board Flex	CEC 32100-4.9	AEC-Q200-21	3mm Type 1, 2mm Type 2, Measurement at 24 ± 2 hours after test conclusion

POST ENVIRONMENTAL STRESS LIMIT

DIELECTRIC	DISSIPATION FACTOR (MAXIMUM)	CAPACITANCE SHIFT	INSULATION RESISTANCE
NPO	≤ 4 10 ⁻³	±2%	10% initial limit
N2T	≤ 6 10 ⁻³	±4%	10% initial limit
X7R	≤ 0.035	±15%	10% initial limit

SPACE LEVEL COMPONENT SCREENED AND QUALIFIED ACCORDING TO ESCC-3009

SRT-Microcéramique can propose a wide range of BME and PME component qualified and tested according to ESCC-3009 standard for space projects. Both for development en evaluation (D32) and flight ready with full lot validation and ESCC standard documentation. Specific qualification programmes can be included to meet final customer requirement.

PRODUCTION CONTROL/SCREENING

Tests conducted on each lot and screening for evaluation components D32 and flying components D30

FREQUENCY	TEST/STRESS	REFERENCE	DETAIL
Lot	DPA	ESCC-23400	Construction analysis
3/Lot	Dimension/weight	ESCC-20400/20500	Dimension in spec/max weight in spec
100%	Burn-In	ESCC-3009	168H, max T°, 2Ur Ur<500V, 1.5Ur Ur=500V, 1.3Ur 500V<Ur≤1250V, 1Ur Ur>1250V (fail<5%)
100%	Room Temperature Electrical Measurements	ESCC-3009	Cp, DF, IR, VP according to datasheet
5/lot	High and Low Temperatures Electrical Measurements	ESCC-3009	0 fail
100%	Visual Inspection	ESCC-20400/20500	

LOT VALIDATION

Lot validation for flying components D30

FREQUENCY	TEST/STRESS	REFERENCE	DETAIL
20/Lot	PCB Mounting, Rapid Change of Temperature, Steady State Humidity, external visual inspection	ESCC-3009/ IEC 60384-1/IEC 60068-2-14	
20/Lot	PCB Mounting, Life test	ECSS-3009/IEC 60384-1	1000H, max T°, 2Ur Ur<500V, 1.5Ur Ur=500V, 1.3Ur 500V<Ur≤1250V, 1Ur Ur>1250V
6/Lot	PCB Mounting, Temperature Characterisation, Robustness of Terminations	ESCC-3009/ IEC 60068-2-14/IEC 60384-1	
6/Lot	Solderability, Permanence of Marking	ECSS-3009/ IEC 60068-2-58/ ECSS-24800	

SPACE LEVEL COMPONENT SCREENED ACCORDING TO COTS+ ECSS-Q-ST-60-13C-REV1

SRT-Microcéramique can apply the COTS+ qualification framework to any suitable component AEQ-200 or not, to make them fly ready, offering a wide range of possibilities at competitive cost, either in Class 1 (COTS1), Class 2 (COTS2) or Class 3 (COTS3).

EVALUATION/SCREENING/LAT

Class 1 (COTS1), Class 2 (COTS2), Class 3 (COTS3)

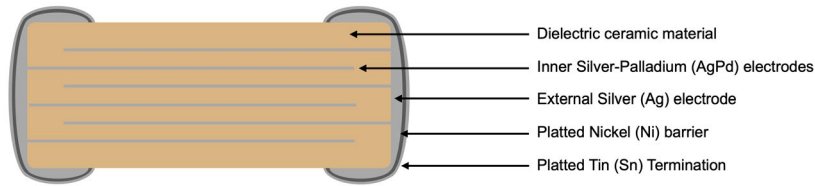
AECQ-200	CLASS 1	CLASS 2	CLASS 3	CATEGORY	TEST TYPE	SAMPLE	PROCEDURE
Yes	X	X	X	Evaluation	Construction Analysis	5	ESCC21001
Yes	X	X	X	Evaluation	Temperature characterization	5	ESCC3009 8.10
Yes	X			Evaluation	Life Test 2000h	40	ESCC3009 8.6 + 8.9
Yes	X			Screening	Complete screening	100%	ESCC3009 chart F3
Yes	X	X	X	LAT	DPA	3	ESCC21001
Yes	X	X		LAT	Life Test 1000h	20	ESCC3009 8.6 + 8.9
No	X	X	X	Evaluation	Construction Analysis	5	ESCC21001
No	X	X	X	Evaluation	Temperature characterization	5	ESCC 3009 8.10
No	X	X		Evaluation	Complete evaluation	72	ESCC 3009 chart F4
No			X	Evaluation	Life Test 1000h	40	ESCC3009 8.6 + 8.9
No	X	X	X	Screening	Complete screening	100%	ESCC3009 chart F3
No	X	X	X	LAT	DPA	3	ESCC21001
No	X			LAT	Complete LAT	52	ESCC 3009 chart F4
No		X	X	LAT	Life Test 1000h	20	ESCC3009 8.6 + 8.9

TINNING

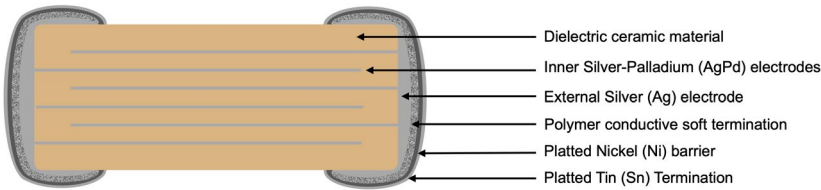
All component for space application can be proposed with dipped SnPb termination (Sn62 Pb36 Ag2) or SAC 305 (Sn96.5 Ag3 Cu0.5) for maximum reliability and whiskers avoidance.

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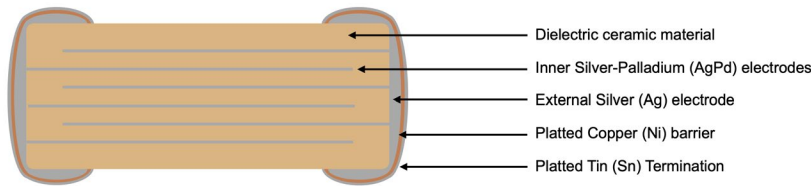
PME (Precious Metal Electrodes)



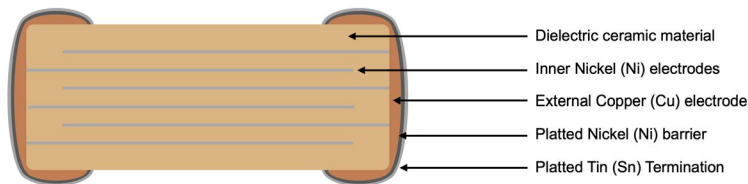
PME (Precious Metal Electrodes) Polymer Soft Termination



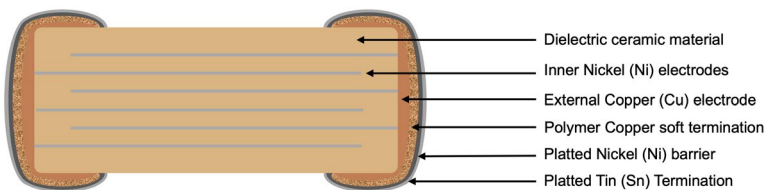
PME (Precious Metal Electrodes) Non Magnetic



BME (Basis Metal Electrodes) code BM



BME (Basis Metal Electrodes) code BM Polymer Soft Termination



REACH Compliance

- SRT-Microcéramique delivers non-chemical articles only.
- These contain no substances which are intended to be released under normal or reasonably foreseeable conditions of use according to Reach article 7(1).

SRT-Microcéramique confirms hereby that our products contain none of the substances which are listed in the present candidate list of the European Chemicals Agency (ECHA), above a concentration of 0.1% by weight of the whole component.

Candidate list of substances (European Chemicals Agency ECHA) :
<http://echa.europa.eu/fr/candidate-list-table>

ROHS COMPLIANCE

SRT-Microcéramique herewith confirms that RoHS-compliant SRT-microcéramique products are conforming to the following EU directives:
EU directive 2015/863/EU EU directive 2011/65/EU EU directive 2003/11/EC

Following restricted materials are not used and do not exceed the legal limits: Lead (Pb, see exemptions),

- Mercury (Hg)
- Cadmium (Cd)
- Chromium (Cr VI)
- Polybrominated biphenyls (PBB) Polybrominated diphenyl ethers (PBDE) Bis(2-Ethylhexyl) phthalate (DEHP) Benzyl butyl phthalate (BBP)
- Dibutyl phthalate (DBP) Diisobutyl phthalate (DIBP)

Exemptions: The following exemptions according to the RoHS annexe are applicable:

Identity 7(a) :

- Lead in high melting temperature type solders (i.e lead-based alloys containing 85% by weight or more lead).

Identity 7(c)-I :

- Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.

The components are suitable for a lead-free process according to EN 60068-2-58 and in accordance with the IPC/JEDEC standard J-Std-020D. The lead free process has been tested using solder alloy Sn96.5Ag3Cu0.5

Export controls and dual-use regulations

Some SRT-Microcéramique components fall under 'dual-use' items under international export controls definition - those that can be used for civil or military purposes which meet certain specified technical standards.

The defining criteria for a dual use component is one with a voltage rating of >750Vdc and a capacitance value of >250nF when measured at 750Vdc and a series inductance <10nH. Components defined as dual-use under the above criteria may require a licence for export across international borders. Please contact us for further information on specific part numbers.

ISO9001:2015

In their design, research and development as well as the manufacturing of MLCC capacitors, customer service and distribution SRT-Microcéramique uses and maintains a Management System audited and certified in accordance to : **ISO9001:2015**

You may contact us for any inquiry regarding the regulations and compliance listed above.